End of Life Notification

Tflex HD400 - Thermal Interface Material

January 25th, 2024

Dear Laird Valued Customer:

This letter is to inform you that Laird™ Tflex HD400 Gap filler material will be transitioning through an end of life (EOL) process. The primary reasons for implementing EOL is diminishing demand. We wish to alert you that the final buy date to submit a purchase order for this product will be July 31st, 2024. Laird's final ship date will be December 31, 2024.

Laird has many other gap filler materials that can replace Tflex HD400 in your application. Some options may include Tflex HD300 (2.7 W/mK) or Tflex HD700 (5 W/mK), comparison shown below.

Typical Property	Tflex HD300	Tflex HD400	Tflex HD700
Thermal Conductivity (W/mk)	2.7	4	5
Thickness Range	0.5 mm (0.010") - 5.0mm (0.20")	0.5 mm (0.020") - 5.0mm (0.20")	0.5 mm (0.020") - 5.0mm (0.20")
Density (g/cc)	3.1	3.0	3.3
Hardness (Shore 00, 3 sec)	38	44	54
Outgassing TML (%)	0.39	0.22	0.23
Outgassing CVCM (%)	0.10	0.04	0.07
Rth@ 40 mils, 10 psi	0.47°C–in2/W	0.36°C–in2/W	0.28°C–in2/W
Dielectric Constant	6.6	10	5

We thank you for your continued business and support. If you have any questions, please contact the Laird Performance Materials sales representative in your region.

Erin Swanbeck

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DuPont Electronics & Industrial